



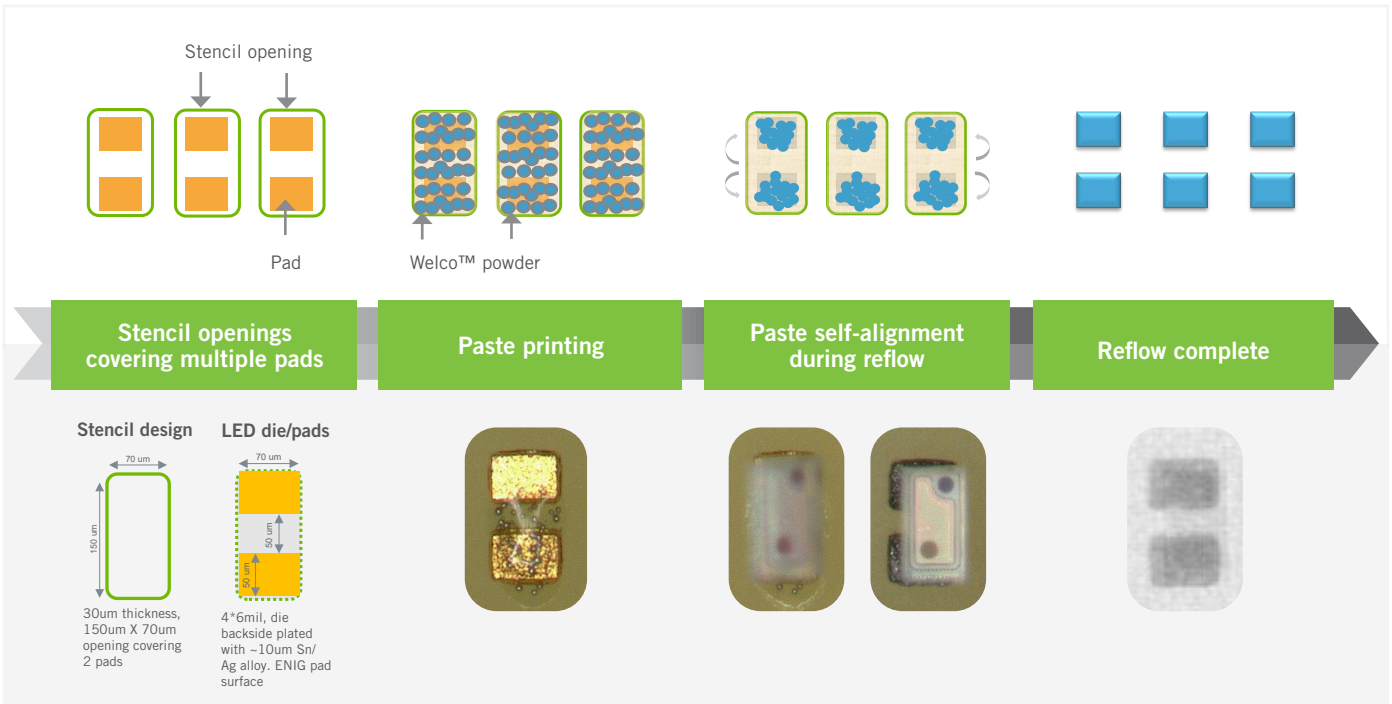
Welco™ LED101 No-Clean SAC305 T6 Paste

Welco™ LED101 SAC305 T6 paste is a state-of-the-art no-clean printing paste engineered for mini-LED and micro-LED attach, or SiP applications. The paste is designed to be printed through stencil openings covering 2 or more substrate pads each and self-align to the pads after reflow without bridging. The LED101 solder paste also possesses high tackiness to facilitate the effective transfer of mini and micro-LED dies. The LED101 series uses only Heraeus Electronics proprietary Welco™ powders to achieve low voids and high yield solder joints for customers' ultra-fine pitch applications.

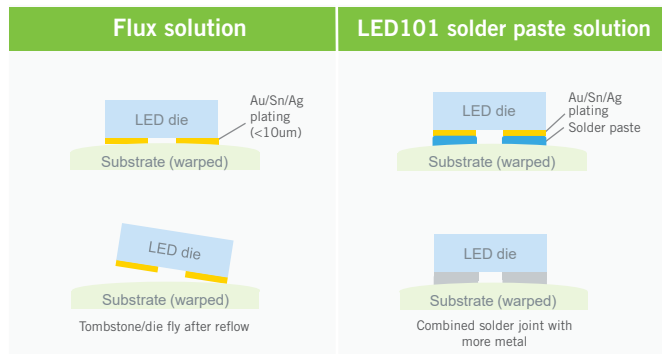
Key features

- Uses high-quality Welco™ Type 6 powders
- No clean and halogen free chemistry
- Self-alignment during reflow
- Best-in-class low-voids performance
- Better solder joint reliability than using pure flux
- Long stencil life (≥ 8 hr) & staging life (≥ 8 hr)
- High tackiness for effective mini and micro-LED die transfer process

Feature 1: Welco™ LED101 solder paste with self-alignment property

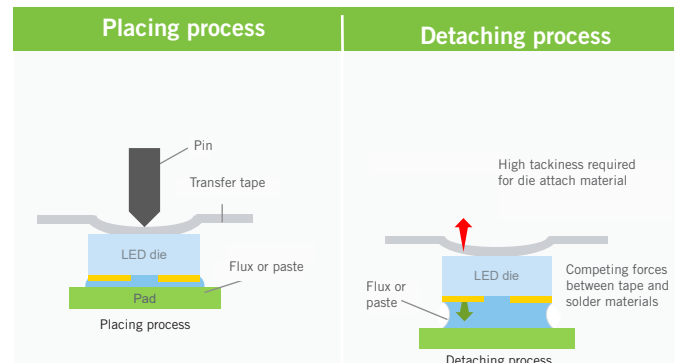


Feature 2: Higher solder joint reliability



- As mini and micro-LED dies get smaller, there is insufficient solder to hold the dies if flux alone is used.
- Metal powders in paste help promote metal coalescence, pulling dies to the substrate and reducing cold joint.

Feature 3: High tackiness for effective die transfer



- Welco™ LED101 provides high tackiness for effective die transfer.

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The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular application. The Heraeus logo, Heraeus, Welco® and the Welco figurative mark are trademarks or registered trademarks of Heraeus Holding GmbH or its affiliates. All rights reserved.

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